

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	228	((die or wafer or chip or integrated adj circuit or ic) near2 (bond or bonding or attachment or attaching or bonded or attached) or flip adj chip or chip-on-chip) and (barrier or corrosion or contamination or crack or sealing or seal or ridge or hermetic or hermetically) near3 (edge or periphery or peripheral or outside or outer or border) near3 (metal or copper or cu or metallic or aluminum or al or nickel or ni or gold or au or silver or ag or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:11
L3	14	(wafer) near2 (scale or level) near10 (bond or bonding or attachment or attaching or bonded or attached or flip adj chip or chip-on-chip) near10 (barrier or corrosion or contamination or crack or sealing or seal or ridge or hermetic or hermetically) near10 (edge or periphery or peripheral or outside or outer or border or metal or copper or cu or metallic or aluminum or al or nickel or ni or gold or au or silver or ag or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 10:15
L4	841	(wafer) near2 (scale or level) same (bond or bonding or attachment or attaching or bonded or attached or flip adj chip or chip-on-chip) and (barrier or corrosion or contamination or crack or sealing or seal or ridge or hermetic or hermetically) near10 (edge or periphery or peripheral or outside or outer or border or metal or copper or cu or metallic or aluminum or al or nickel or ni or gold or au or silver or ag or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:13
L5	265	(wafer) near2 (scale or level) near6 (bond or bonding or attachment or attaching or bonded or attached or flip adj chip or chip-on-chip) and (barrier or corrosion or contamination or crack or sealing or seal or ridge or hermetic or hermetically) near10 (edge or periphery or peripheral or outside or outer or border or metal or copper or cu or metallic or aluminum or al or nickel or ni or gold or au or silver or ag or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 09:13
L6	45	(wafer) near2 (scale or level) near4 (package or packaging) and (barrier or corrosion or contamination or crack or sealing or seal or ridge or hermetic or hermetically) near10 (edge or periphery or peripheral or outside or outer or border) near10 (metal or copper or cu or metallic or aluminum or al or nickel or ni or gold or au or silver or ag or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 10:14
L7	1187	(wafer) near2 (edge or border or outside or outer or peripheral or periphery or circumscrib\$3) near8 (metal or copper or cu or metallic or aluminum or al or nickel or ni or gold or au or silver or ag or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 10:16
L8	186	(wafer) near2 (edge or border or outside or outer or peripheral or periphery or circumscrib\$3) near15 (barrier or ridge or seal or sealing or sealed or hermetic\$5 or raised or protrusion or protruding or blocking or contaminant or corrosion or corrod\$3 or crack) near15 (metal or copper or cu or metallic or aluminum or al or nickel or ni or gold or au or silver or ag or solder)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/07 10:18